High Voltage Silicon Pin Diode

These devices are designed primarily for VHF band switching applications but are also suitable for use in general–purpose switching circuits. They are supplied in a cost–effective plastic surface mount package for economical, high–volume consumer and industrial requirements.

- Long Reverse Recovery Time $t_{TT} = 300 \text{ ns (Typ)}$
- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Series Resistance @ 100 MHz R_S = 0.7 Ohms (Typ) @ I_F = 10 mAdc
- Reverse Breakdown Voltage = 200 V (Min)
- Device Marking: 4R



Symbol	Rating	Value	Unit
٧ _R	Continuous Reverse Voltage	200	Vdc
lF	Peak Forward Current	20	mAdc

THERMAL CHARACTERISTICS

Symbol	Characteristic	Max	Unit
PD	Total Device Dissipation FR–5 Board,* T _A = 25°C Derate above 25°C	200 1.57	mW mW/°C
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	635	°C/W
T _J , T _{stg}	Junction and Storage Temperature	150	°C

^{*}FR-4 Minimum Pad



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SILICON PIN SWITCHING DIODE



PLASTIC SOD-323 CASE 477



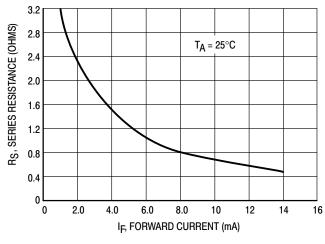
ORDERING INFORMATION

Device	Package	Shipping
MMVL3700T1	SOD-323	3000 / Tape & Reel

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μAdc)	V(BR)R	200	_	_	Vdc
Diode Capacitance (V _R = 20 Vdc, f = 1.0 MHz)	C _T	_	_	1.0	pF
Series Resistance (I _F = 10 mAdc)	RS	_	0.7	1.0	Ω
Reverse Leakage Current (V _R = 150 Vdc)	IR	_	_	0.1	μAdc
Reverse Recovery Time (I _F = I _R = 10 mAdc)	t _{rr}	_	300	_	ns

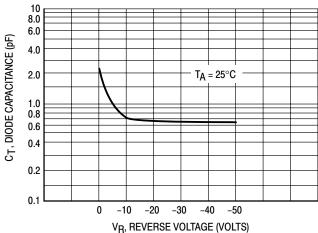
TYPICAL CHARACTERISTICS



800 700 I F , FORWARD CURRENT (mA) 600 500 T_A = 25°C 400 300 200 100 0 0.7 1.0 VF, FORWARD VOLTAGE (VOLTS)

Figure 1. Series Resistance

Figure 2. Forward Voltage 100



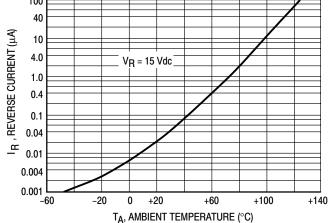
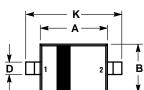


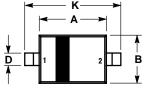
Figure 3. Diode Capacitance

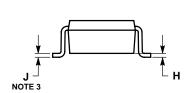
Figure 4. Leakage Current

PACKAGE DIMENSIONS



SOD-323 PLASTIC PACKAGE CASE 477-02 ISSUE A







- NOTES:

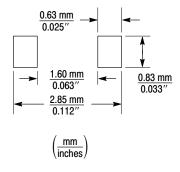
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.60	1.80	0.063	0.071	
В	1.15	1.35	0.045	0.053	
С	0.80	1.00	0.031	0.039	
D	0.25	0.40	0.010	0.016	
Е	0.15 REF		0.006 REF		
Н	0.00	0.10	0.000	0.004	
J	0.089	0.177	0.0035	0.0070	
К	2.30	2.70	0.091	0.106	

STYLE 1: PIN 1. CATHODE 2. ANODE



SOD-323 Soldering Footprint

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